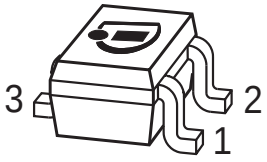
NPN Silicon RF Transistor*



- For low distortionbroadband amplifiers and oscillators up to 2 GHz at collector currents from 5 mA to 30 mA
- Pb-free (RoHS compliant) package[1)]
- Qualified according AEC Q101

* Short term description

ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR93AW	R2s	1=B	2=E	3=C	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	12	V
Collector-emitter voltage	V_{CES}	20	
Collector-base voltage	V_{CBO}	20	
Emitter-base voltage	V_{EBO}	2	
Collector current	I_C	90	mA
Base current	I_B	9	
Total power dissipation[2)] $T_S \leq 104$ °C	P_{tot}	300	mW
Junction temperature	T_j	150	°C
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[3)]	R_{thJS}	≤ 155	K/W

[1]Pb-containing package may be available upon special request

[2]T_S is measured on the collector lead at the soldering point to the pcb

[3]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 1 mA, I_B = 0	$V_{(BR)CEO}$	12	-	-	V
Collector-emitter cutoff current V_{CE} = 20 V, V_{BE} = 0	I_{CES}	-	-	100	µA
Collector-base cutoff current V_{CB} = 10 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 2.5 V, I_C = 0	I_{EBO}	-	-	10	µA
DC current gain- I_C = 30 mA, V_{CE} = 8 V, pulse measured	h_{FE}	70	100	140	-

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency I_C = 15 mA, V_{CE} = 8 V, f = 500 MHz	f_T	4.5	6	-	GHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz, V_{BE} = 0 , emitter grounded	C_{cb}	-	0.58	0.8	pF
Collector emitter capacitance V_{CE} = 10 V, f = 1 MHz, V_{BE} = 0 , base grounded	C_{ce}	-	0.3	-	
Emitter-base capacitance V_{EB} = 0.5 V, f = 1 MHz, V_{CB} = 0 , collector grounded	C_{eb}	-	1.9	-	
Noise figure I_C = 5 mA, V_{CE} = 8 V, Z_S = Z_{Sopt}, f = 900 MHz I_C = 5 mA, V_{CE} = 8 V, Z_S = Z_{Sopt}, f = 1.8 GHz	F	 - -	 1.5 2.6	 - -	dB
Power gain, maximum available[1)] I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_{Sopt}, Z_L = Z_{Lopt} , f = 900 MHz I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_{Sopt}, Z_L = Z_{Lopt}, f = 1.8 GHz	G_{ma}	 - -	 15.5 10.5	 - -	
Transducer gain I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_L = 50 Ω, f = 900 MHz I_C = 30 mA, V_{CE} = 8 V, Z_S = Z_L = 50 Ω, f = 1.8 MHz	$\lvert S_{21e}\rvert^2$	 - -	 13 7.5	 - -	dB

[1] $G_{ma} = |S_{21e} / S_{12e}| (k-(k^2-1)^{1/2})$

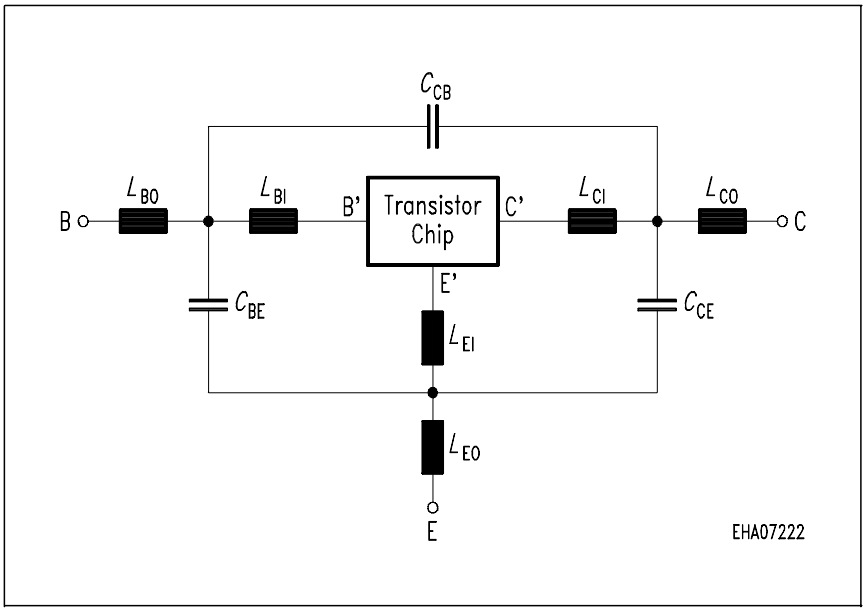
SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):

Transistor Chip Data:

IS =	8.6752	fA	BF =	137.63	-	NF =	0.93633	-
VAF =	20.011	V	IKF =	0.33395	A	ISE =	2619.3	fA
NE =	1.5466	-	BR =	59	-	NR =	0.88761	-
VAR =	26.834	V	IKR =	0.015129	A	ISC =	0.70823	fA
NC =	1.95	-	RB =	7.2326	Ω	IRB =	0.043806	mA
RBM =	3.4649	Ω	RE =	1.0075	-	RC =	0.13193	Ω
CJE =	3.1538	fF	VJE =	0.70393	V	MJE =	0.5071	-
TF =	33.388	ps	XTF =	0.28319	-	VTF =	0.17765	V
ITF =	2.5184	mA	PTF =	0	deg	CJC =	1039.5	fF
VJC =	0.72744	V	MJC =	0.34565	-	XCJC =	0.21442	-
TR =	1.1061	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.75935		TNOM	300	K

All parameters are ready to use, no scalling is necessary. Extracted on behalf of Infineon Technologies AG by: Institut für Mobil- und Satellitentechnik (IMST)

Package Equivalent Circuit:

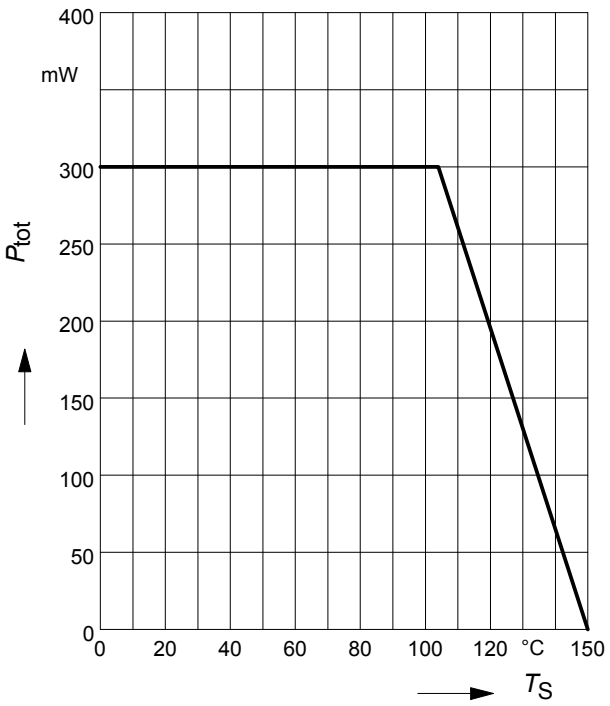


L_{BI} =	0.57	nH
L_{BO} =	0.4	nH
L_{EI} =	0.43	nH
L_{EO} =	0.5	nH
L_{CI} =	0	nH
L_{CO} =	0.41	nH
C_{BE} =	61	fF
C_{CB} =	101	fF
C_{CE} =	175	fF

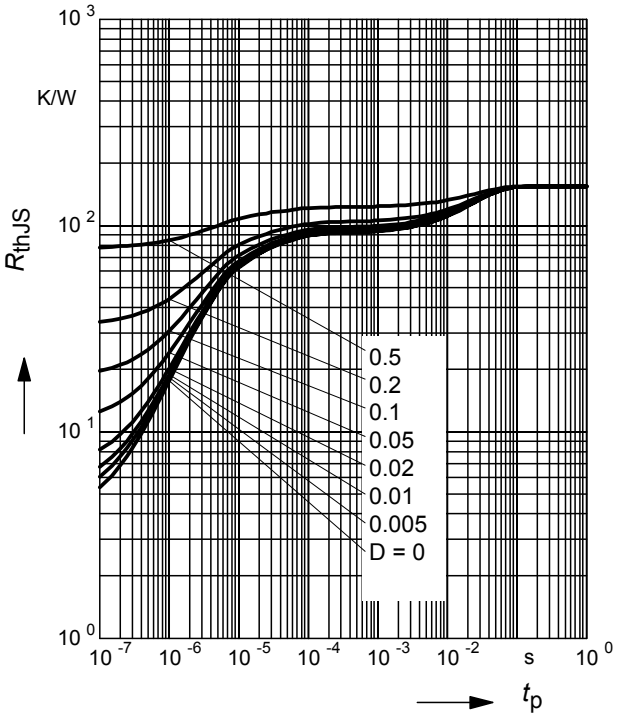
Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: http://www.infineon.com

Total power dissipation $P_{tot} = f(T_S)$

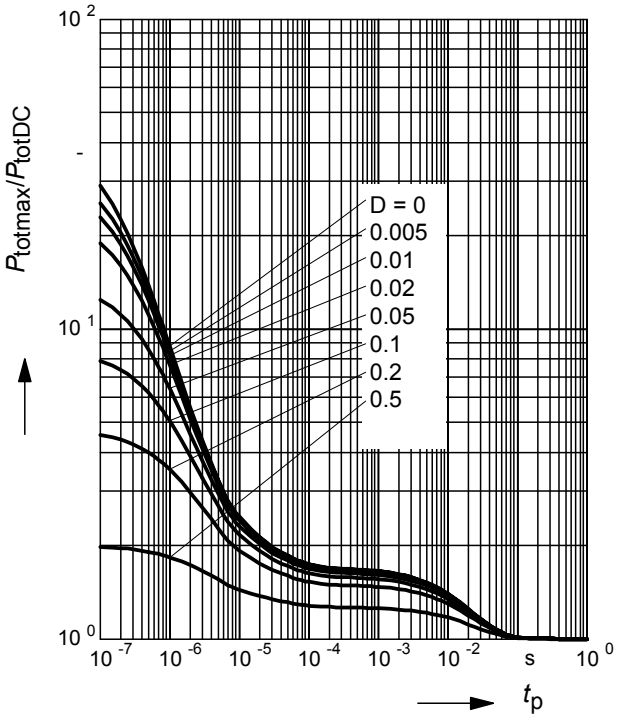


Permissible Pulse Load $R_{thJS} = f(t_p)$

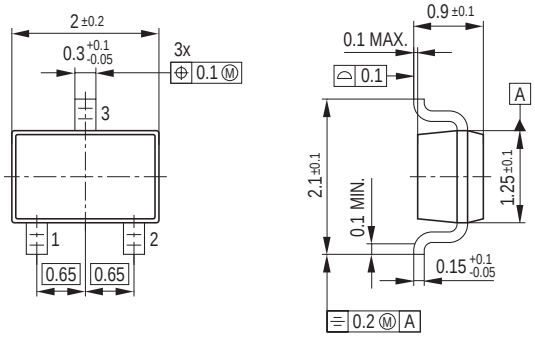


Permissible Pulse Load

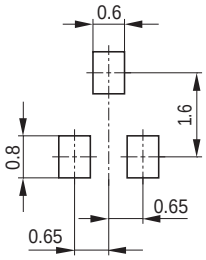
$P_{totmax}/P_{totDC} = f(t_p)$



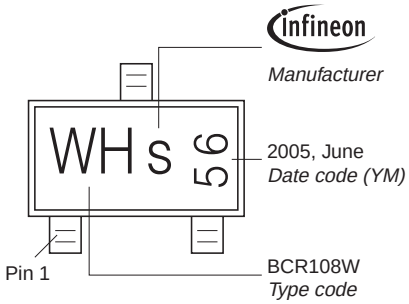
Package Outline



Foot Print

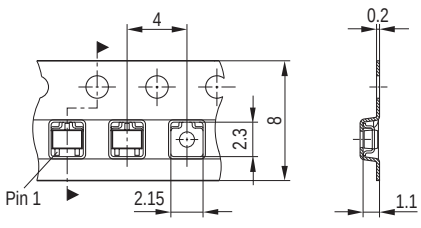


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



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